Title (en)

Microstrip antenna

Title (de)

Mikrostreifenleiterantenne

Title (fr)

Antenne microruban

Publication

EP 0831547 A2 19980325 (EN)

Application

EP 97116094 A 19970916

Priority

JP 25014096 A 19960920

Abstract (en)

A microstrip antenna (1) has a dielectric-made substrate (11). A first radiation-electrode (12) is formed on one main surface of the substrate (11). Second radiation-electrodes (13, 14) are formed on the periphery of the first radiation-electrode (12) with a spacing between the first radiation-electrode (12) and each of the second radiation electrodes (13, 14). A ground electrode (15) is formed on the other main surface of the substrate (11). A power-feeding through-hole 16 is provided at a position corresponding to the first radiation-electrode (12) on the substrate (11). A plurality of through-holes (17) are provided at positions corresponding to the second radiation-electrode (13) on the substrate (11). Capacitive-coupling portions (18a, 18b) are provided to capacitively couple the first radiation-electrode (12) and the second radiation-electrodes (13, 14), respectively. A connector (19), serving as a coaxial line, for feeding power to the first radiation electrode (12) is inserted into and past the feeding through-hole (16) from the other main surface of the substrate (11). The connector (19) is electrically connected to the first radiation-electrode (12) with solder (20a) and is fixed to the substrate (11) with solder (20a, 20b). The second radiation-electrodes (13, 14) are connected to the ground electrode (15) via the through-holes (17). <IMAGE>

IPC 1-7

H01Q 9/04

IPC 8 full level

H01Q 13/08 (2006.01); **H01Q 5/10** (2015.01); **H01Q 9/04** (2006.01); **H01Q 19/00** (2006.01)

CPC (source: EP)

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